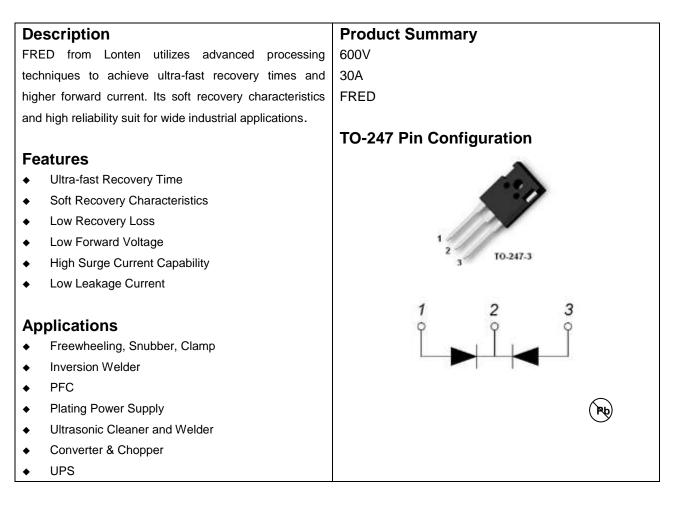


600V 30A Ultra-fast Recovery Diode



Absolute Maximum Ratings T_c = 25°C unless otherwise noted

Parameter	Symbol	Value	Unit
Maximum D.C. Reverse Voltage	V _R	600	V
Maximum Repetitive Reverse Voltage	V _{RRM}	600	V
Average Forward Current(Tc = 110°C,Per Diode)		15	А
Average Forward Current(Tc = 110°C,Per Package)	I _{F(AV)}	30	А
RMS Forward Current(Tc = 110°C)	I _{F(RMS)}	21	А
Non-Repetitive Surge Forward Current(TJ =	I _{FSM}	150	А
45℃,t=10ms,50Hz,Sine)			
Power Dissipation	P _D	96	W
Junction Temperature Range	TJ	-55 to +150	°C
Storage Temperature Range	T _{STG}	-55 to +150	°C
Module-to-Sink(Recommended M3)	Torque	1.1	Nm
	Weight	6.0	g



Thermal Characteristics

Parameter	Symbol	Value	Unit
Thermal Resistance, Junction-to-Case	R _{eJC}	1.3	°C/W

Package Marking and Ordering Information

Device	Device Package	Marking
LMB60U30W4	TO-247	LMB60U30W4

Electrical Characteristics T_J = 25°C unless otherwise noted

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
I _{RM} R	Reverse Leakage Current	V _R =600V			10	uA
		V _R =600V, TJ=125℃			10	mA
V _F Forward Voltage	I _F =15A		2.0	2.4	V	
	Forward voltage	I _F =15A, TJ=125℃		1.6		V
t _{rr} Revers	Reverse Recovery Time	I _F =1A, V _R =30V,		18		ns
	Reverse Recovery Time	di _F /d _t =-200A/us				
t _{rr}	Reverse Recovery Time	VR=300V, IF=15A		25		ns
I _{RRM}	Max. Reverse Recovery Current	di_F/d_t =-200A/us, T _J =25 $^\circ$ C		2.5		А
t _{rr}	Reverse Recovery Time	− V _R =300V, I _F =15A − di _F /d _t =-200A/us, T _J =125℃		90		ns
I _{RRM}	Max. Reverse Recovery Current			5.5		А
S				1.9		

Electrical Characteristics Diagrams

Figure 1. Forward Voltage Drop vs Forward Current

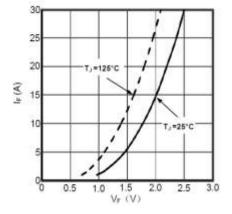
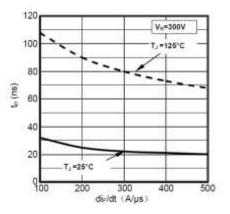


Figure 2. Reverse Recovery Time vs diF/dt





LMB60U30W4

Figure 3. Reverse Recovery Current vs diF/dt

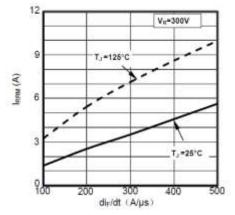


Figure 5.Forward current vs Case temperature

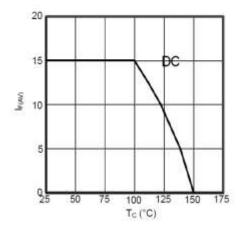


Figure 4. Reverse Recovery Charge vs diF/dt

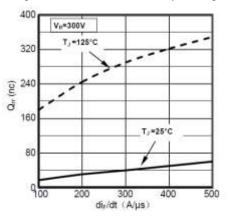


Figure6. Transient Thermal Impedance

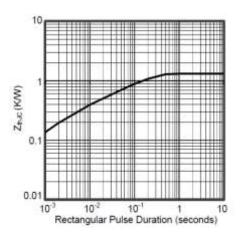


Figure7. Diode Reverse Recovery Test Circuit and Waveform

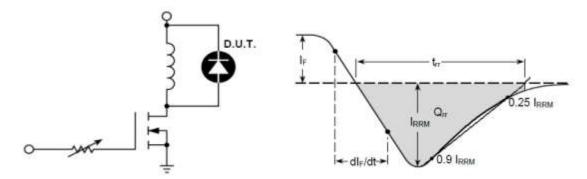
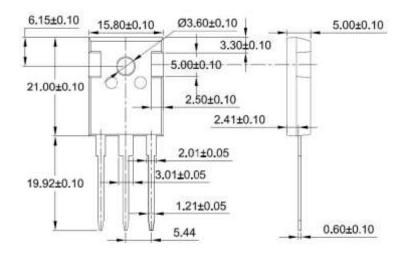
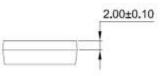


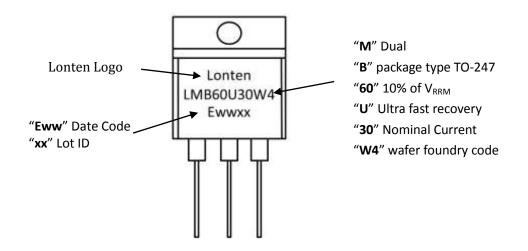


Figure8. Package Outline Dimensions in Millimeters





Marking Information





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